APPLICABLE STANDARD				
Rating	Operating Temperature Range	-55 °C to 85 °C (1)	Storage Temperature Range	-40 °C to 60 °C (2)
	Voltage	50 V AC/DC	Storage Humidity Range	Relative humidity 85% max (Not dewed)
	Current	0.4 A	Operating Humidity Range	

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
General Examination	Visually and by measuring instrument.	According to drawing.	×	×
Marking	Confirmed visually.		×	×
ELECTRIC CHARACTERISTICS				
Contact Resistance	100 mA(DC or 1000Hz)	60mΩ MAX.	×	—
Insulation Resistance	100 V DC.	50 MΩ MIN.	×	—
Voltage Proof	200 V AC for 1 min.	No flashover or breakdown.	×	—
MECHANICAL CHARACTERISTICS				
Insertion and Withdrawal Forces	Measured by applicable connector.	Insertion Force: 36 N MAX. Withdrawal Force: 4.8 N MIN.	×	—
Mechanical Operation	10 times insertions and extractions.	① Contact Resistance : 80mΩ MAX. ② No damage, crack and looseness of parts.	×	—
Vibration	Frequency 10 to 55 to 10Hz, approx 5min Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.	① No electrical discontinuity of 1 μs. ② No damage, crack and looseness of parts.	×	—
Shock	490 m/s^2 , duration of pulse 11 ms at 3 times for 3 both axial directions.		×	—
ENVIRONMENTAL CHARACTERISTICS				
Damp Heat (Steady state)	Exposed at 40±2 °C, 90 ～ 95 %, 96±4 h.	① Contact Resistance : 80mΩ MAX. ② Insulation Resistance : 50 MΩ MIN.	×	—
Rapid Change of Temperature	Temperature -55 → +85 °C Time 30 → 30 min. under 5 cycles. (Relocation time to chamber : within 2～3 MIN)	③ No damage, crack and looseness of parts.	×	—
Cold	Exposed at -55℃, 96±4 h	① Contact Resistance : 80mΩ MAX.	×	—
Dry Heat	Exposed at 85℃, 96±4 h	② No damage, crack and looseness of parts.	×	—
Sulfur Dioxide	Exposed at 25±2℃, 75±5%RH, 25±5 PPM for 96±4 h. (Test standard: IEC 68)	Contact Resistance : 80mΩ MAX.	×	—
Resistance to Soldering Heat	1)Reflow soldering : Peak TMP : 260℃MAX Reflow TMP: 220℃MIN for 60sec 2) Soldering irons : 360℃ MAX. for 5 sec.	No deformation of case of excessive looseness of the terminal.	×	—
Solderability	Soldered at solder temperature 240±3℃ for immersion duration, 3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	—

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△0					

REMARKS (1) Include temperature rise caused by current-carrying.
(2) "STORAGE" means a long-term storage state for the unused product before assembly to PCB.

Unless otherwise specified, refer to IEC 60512.

APPROVED	HT. YAMAGUCHI	20200406
CHECKED	HT. YAMAGUCHI	20200406
DESIGNED	YY. YOSHIHARA	20200403
DRAWN	YY. YOSHIHARA	20200403

Note QT:Qualification Test AT:Assurance Test X:Applicable Test

DRAWING NO. ELC-369481-00-00

HRS

SPECIFICATION SHEET

HIROSE ELECTRIC CO., LTD.

PART NO. FX25-80P-0.4SV

CODE NO. CL575-4002-0-005 △0 2/1

FORM HD0011-2-1

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